

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7399729

<b>SUBMISSION TYPE:</b>	CORRECTIVE ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	Corrective Assignment to correct the 7TH INVENTOR NAME previously recorded on Reel 059982 Frame 0401. Assignor(s) hereby confirms the CORRECT INVENTOR NAME FROM DIAN HAU TO DIAN HAU CHEN.

## CONVEYING PARTY DATA

Name	Execution Date
CHIH-FAN HUANG	09/18/2018
HUNG-CHAO KAO	09/18/2018
YUAN-YANG HSIAO	09/18/2018
TSUNG-CHIEH HSIAO	09/18/2018
HSIANG-KU SHEN	09/18/2018
HUI-CHI CHEN	09/25/2018
DIAN-HAU CHEN	09/25/2018
YEN-MING CHEN	09/25/2018

## RECEIVING PARTY DATA

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<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-78

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17750729

## CORRESPONDENCE DATA

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<b>ATTORNEY DOCKET NUMBER:</b>	2017-3450/24061.3682US03
<b>NAME OF SUBMITTER:</b>	LINDA INGRAM
<b>SIGNATURE:</b>	/Linda Ingram/
<b>DATE SIGNED:</b>	06/24/2022

**Total Attachments: 5**

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**PATENT ASSIGNMENT COVER SHEET**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT																		
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT																		
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<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHIH-FAN HUANG</td> <td>09/18/2018</td> </tr> <tr> <td>HUNG-CHAO KAO</td> <td>09/18/2018</td> </tr> <tr> <td>YUAN-YANG HSIAO</td> <td>09/18/2018</td> </tr> <tr> <td>TSUNG-CHIEH HSIAO</td> <td>09/18/2018</td> </tr> <tr> <td>HSIANG-KU SHEN</td> <td>09/18/2018</td> </tr> <tr> <td>HUI-CHI CHEN</td> <td>09/25/2018</td> </tr> <tr> <td>DIAN HAU</td> <td>09/25/2018</td> </tr> <tr> <td>YEN-MING CHEN</td> <td>09/25/2018</td> </tr> </tbody> </table>		Name	Execution Date	CHIH-FAN HUANG	09/18/2018	HUNG-CHAO KAO	09/18/2018	YUAN-YANG HSIAO	09/18/2018	TSUNG-CHIEH HSIAO	09/18/2018	HSIANG-KU SHEN	09/18/2018	HUI-CHI CHEN	09/25/2018	DIAN HAU	09/25/2018	YEN-MING CHEN	09/25/2018
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Application Number: 17750729

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**Correspondent Name:** HAYNES AND BOONE, LLP  
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**Address Line 4:** DALLAS, TEXAS 75219

**ATTORNEY DOCKET NUMBER:**

2017-3450/24061.3682US03

**NAME OF SUBMITTER:**

LINDA INGRAM

**Signature:**

/Linda Ingram/

**Date:**

05/23/2022

**Total Attachments: 3**

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**RECEIPT INFORMATION**

**EPAS ID:** PAT7344127  
**Receipt Date:** 05/23/2022

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TT (S)

Docket No.: P20173450US00/ 24061.3682US01  
Customer No.: 000042717

**ASSIGNMENT**

WHEREAS, we,

- (1) Chih-Fan Huang of Kaohsiung City, Taiwan (R.O.C.)
- (2) Hung-Chao Kao of Taipei City, Taiwan (R.O.C.)
- (3) Yuan-Yang Hsiao of Taipei, Taiwan (R.O.C.)
- (4) Tsung-Chieh Hsiao of Changhua County, Taiwan (R.O.C.)
- (5) Hsiang-Ku Shen of Hsinchu City, Taiwan (R.O.C.)
- (6) Hui-Chi Chen of Hsinchu County, Taiwan (R.O.C.)
- (7) Dian-Hsu Chen of Hsinchu, Taiwan (R.O.C.)
- (8) Yen-Ming Chen of Hsin-Chu County, Taiwan (R.O.C.)

have invented certain improvements in

**METAL-INSULATOR-METAL STRUCTURE AND METHODS OF FABRICATION THEREOF**

for which we have executed an application for Letters Patent of the United States of America,

  X   of even date filed herewith; and  
           filed on                    and assigned application number                   ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on

Docket No.: P20173450US00/ 24061.3682US01  
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applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chih-Fan Huang

Residence Address: Kaohsiung City, Taiwan (R.O.C.)

Dated: Chih-Fan Huang 2018.9.18 Chih-Fan Huang  
Inventor Signature

Inventor Name: Hung-Chao Kao

Residence Address: Taipei City, Taiwan (R.O.C.)

Dated: 2018/9/18 Hung-Chao Kao  
Inventor Signature

Inventor Name: Yuan-Yang Hsiao

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Dated: 2018/9/18 Yuan-Yang Hsiao  
Inventor Signature

Inventor Name: Tsung-Chieh Hsiao

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Dated: 2018/9/18 TSUNG-Chieh Hsiao  
Inventor Signature

Docket No.: P20173450US00/ 24061.3682US01  
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Residence Address: Hsinchu City, Taiwan (R.O.C.)

Dated: 2018/9/18

Hsiang-Ku Shen  
Inventor Signature

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Residence Address: Hsinchu County, Taiwan (R.O.C.)

Dated: 2018/9/25

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